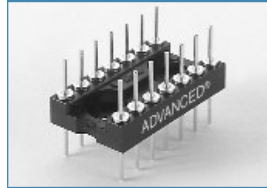
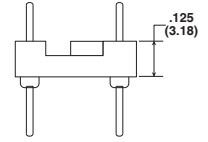


Table of Models

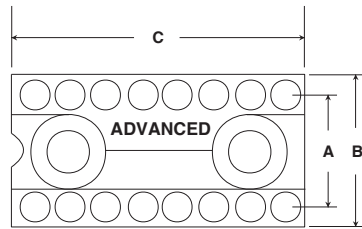


Description: **Molded DIP Adapter (RDA)**
 Material: High Temp. Liquid Crystal Polymer (LCP)
 Index: -40°C to 260°C (-40°F to 500°F)

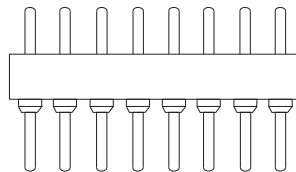


RDA replaces DA and HDA.

Dimensional Information



Terminal Type -09 Shown



# of Pins	A	B	C
8	.300 (7.62)	.400 (10.16)	.400 (10.16)
14	.300 (7.62)	.400 (10.16)	.700 (17.78)
16	.300 (7.62)	.400 (10.16)	.800 (20.32)
18	.300 (7.62)	.400 (10.16)	.900 (22.86)
20	.300 (7.62)	.400 (10.16)	1.000 (25.40)
22	.400 (10.16)	.500 (12.70)	1.100 (27.94)
24	.600 (15.24)	.700 (17.78)	1.200 (30.48)
28	.600 (15.24)	.700 (17.78)	1.400 (35.56)
40	.600 (15.24)	.700 (17.78)	2.000 (50.80)

Features:

- Low profile.
- Design allows for stacking on .100/(2.54mm) grid.
- Board to Board applicable.
- Easily customized to fit your applications.
- Mating sockets available in Open Frame or Closed Frame molded designs and Peel-A-Way® Removable Terminal Carriers.

Specifications:

Terminals:

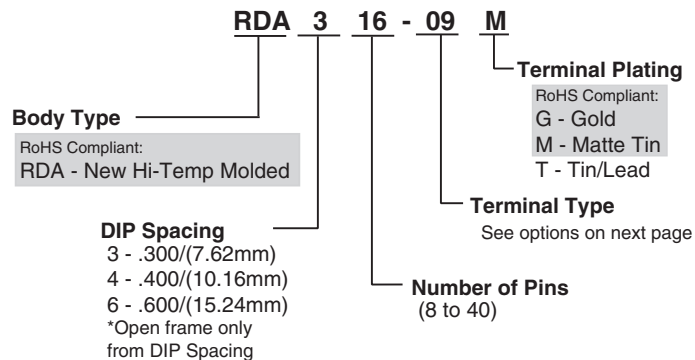
Brass - Copper Alloy
(C36000) ASTM-B-16

Plating:

G - Gold over Nickel
 M - Matte Tin over Nickel
 T - Tin/Lead over Nickel

Gold per MIL-G-45204
 Matte Tin per ASTM545-97
 Tin/Lead per MIL-P-81728
 Nickel per QQ-N-290

How To Order



Note: Quick-Turn delivery is not available on products with Matte Tin plating.



5 Energy Way, West Warwick, RI 02893 USA
 Tel: 800.424.9850 | 401.823.5200
 Fax: 401.823.8723
 info@advanced.com | www.advanced.com
 Cat. 16 Rev. 1

Products shown covered by patents issued and/or pending. Specifications subject to change without notice.

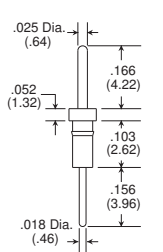
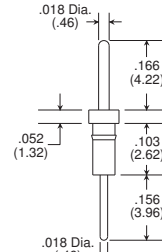
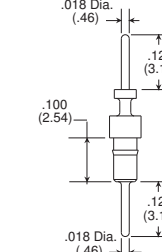
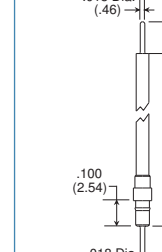
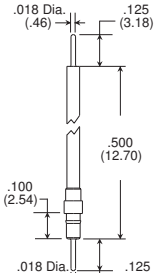
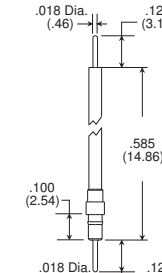
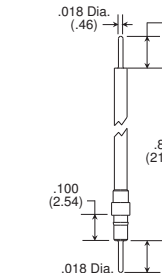
inch/(mm)

Molded DIP Adapters

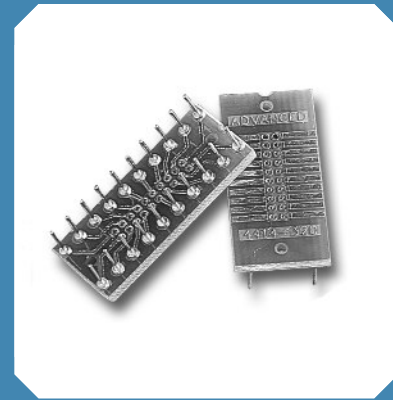
Dual In-Line Adapters / Discrete Component Carriers

Additional standard and custom terminals available.
See Terminals section online or consult factory.

Standard Quick-Turn Terminals

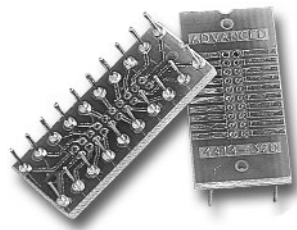
Type -08	Type -09	Type -68	Type -43
			
Type -185	Type -42	Type -71	
			

DIP Adapters

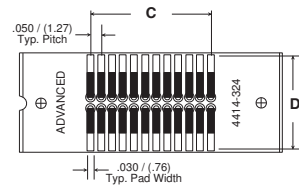


Package Conversion Applications

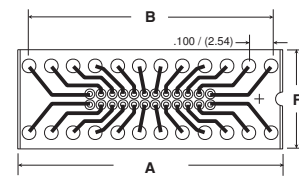
SOIC to DIP Adapters



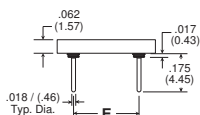
- Wide variety of package conversion adapters available including these standard SOIC to DIP adapters.
- Adapter allows present Gull Wing devices to be solderable or socketable in a thru-hole application.
- Pin spacing allows space for conductor runs on PCB.
- Saves space (X, Y & Z) when used with Advanced sockets.
- Radius ends of adapter pins to improve socketing.
- Allows testing with standard test clips.
- RoHS Compliant designs available on custom orders.



Top View



Bottom View



Side View

Part Numbers	# of Pins	A	B	C	D	E	F
4414-308	8	.400 (10.16)	.300 (7.62)	.150 (3.81)	.445 (11.30)	.300 (7.62)	.450 (11.43)
4414-314	14	.700 (17.78)	.600 (15.24)	.300 (7.62)	.445 (11.30)	.300 (7.62)	.450 (11.43)
4414-316	16	.800 (20.32)	.700 (17.78)	.350 (8.89)	.445 (11.30)	.300 (7.62)	.450 (11.43)
4414-320	20	1.000 (25.40)	.900 (22.86)	.450 (11.43)	.445 (11.30)	.300 (7.62)	.450 (11.43)
4414-324	24	1.200 (30.48)	1.100 (27.94)	.550 (13.97)	.445 (11.30)	.300 (7.62)	.450 (11.43)
4414-628*	28	1.400 (35.56)	1.300 (33.02)	.650 (16.51)	.648 (16.46)	.600 (15.24)	.750 (19.05)
4414-632*	32	1.600 (40.64)	1.500 (38.10)	.750 (19.05)	.648 (16.46)	.600 (15.24)	.750 (19.05)
4414-640*	40	2.000 (50.80)	1.900 (48.26)	.950 (24.13)	.648 (16.46)	.600 (15.24)	.750 (19.05)

*Consult Factory for Availability.

Specifications:

Body Material:

Copper Clad FR-4, Solder Plated
U.L. Rated 94V-0

Thermal Index:

140°C (284°F)

Terminals:

Brass - Copper Alloy
(C36000) ASTM-B-16

Plating:

T - Tin/Lead over Nickel

Tin/Lead per MIL-P-81728
Nickel per QQ-N-290